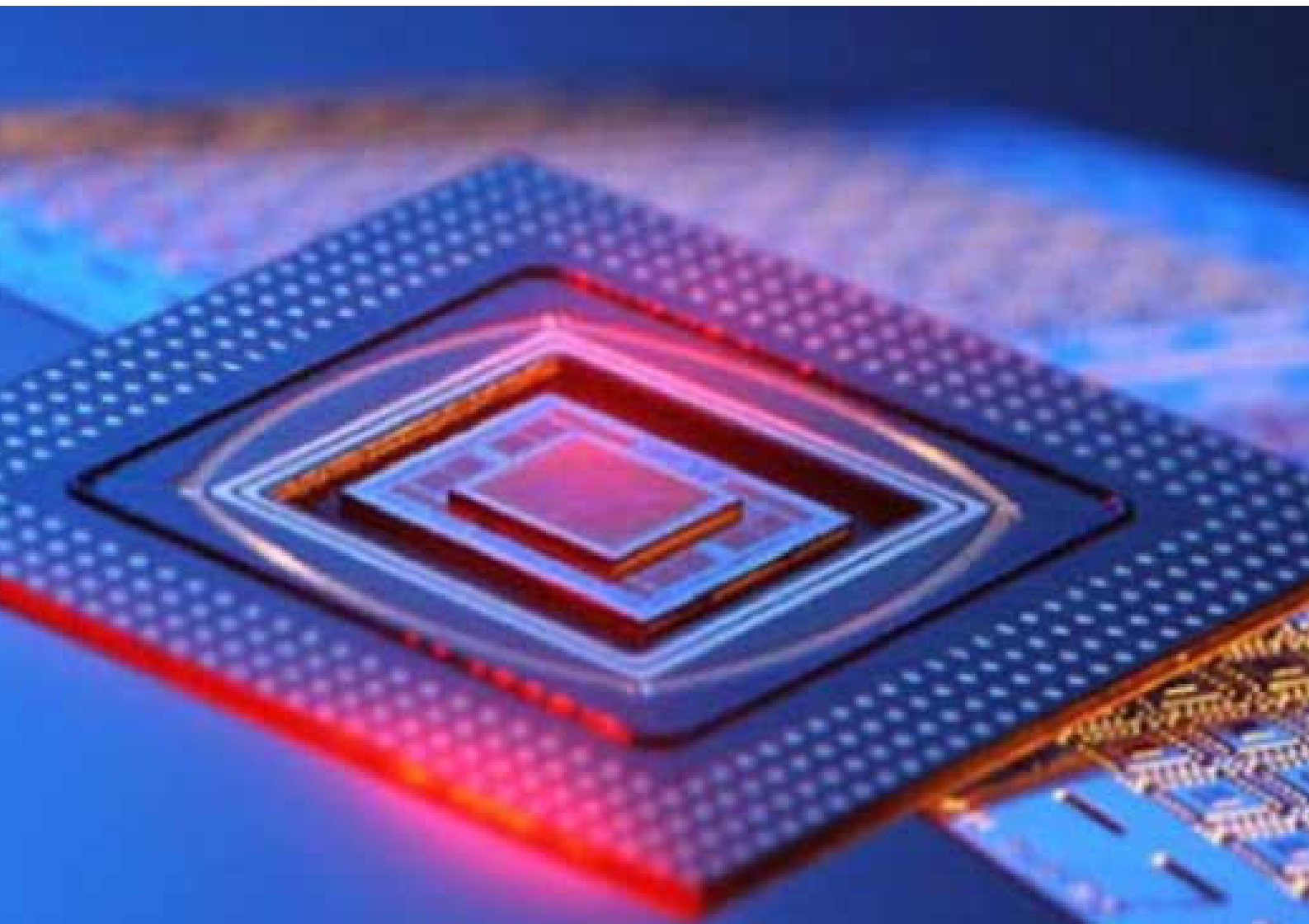


# EVENT REPORT

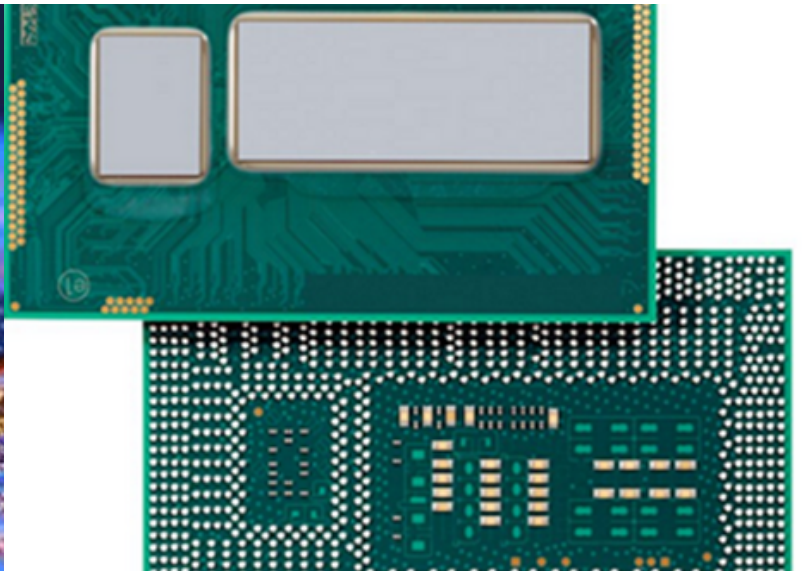
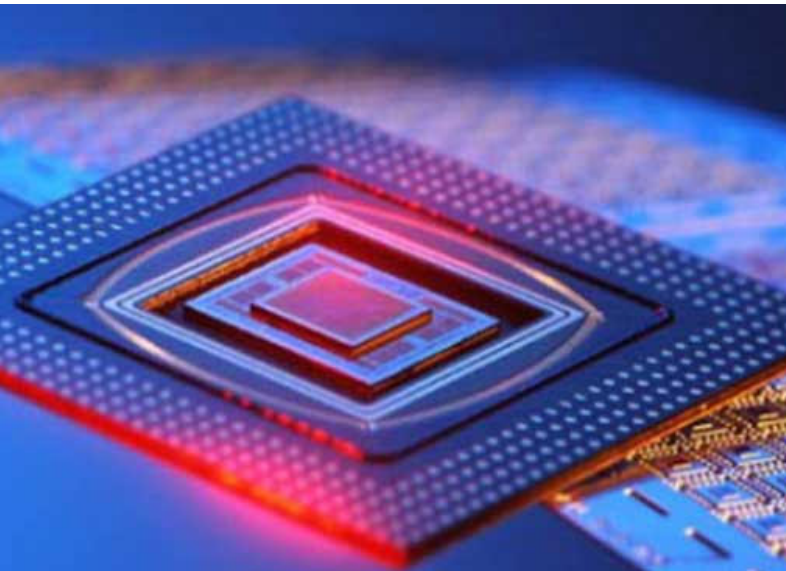
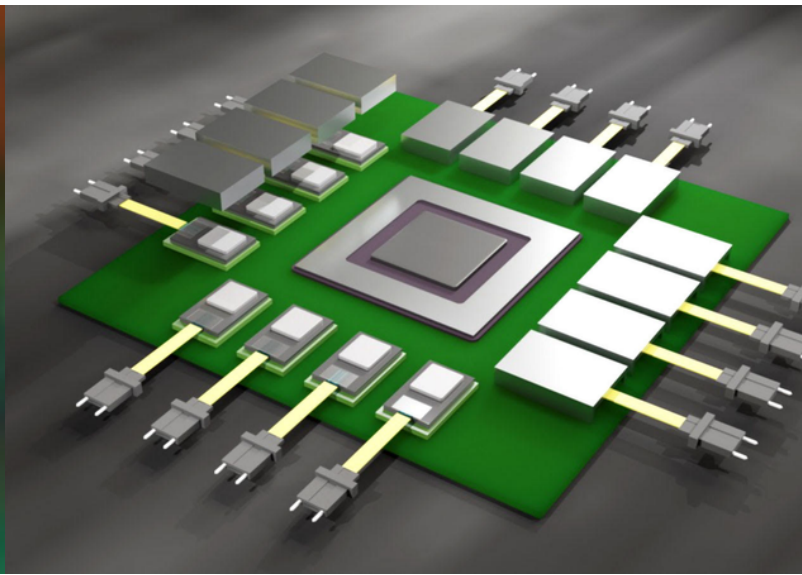
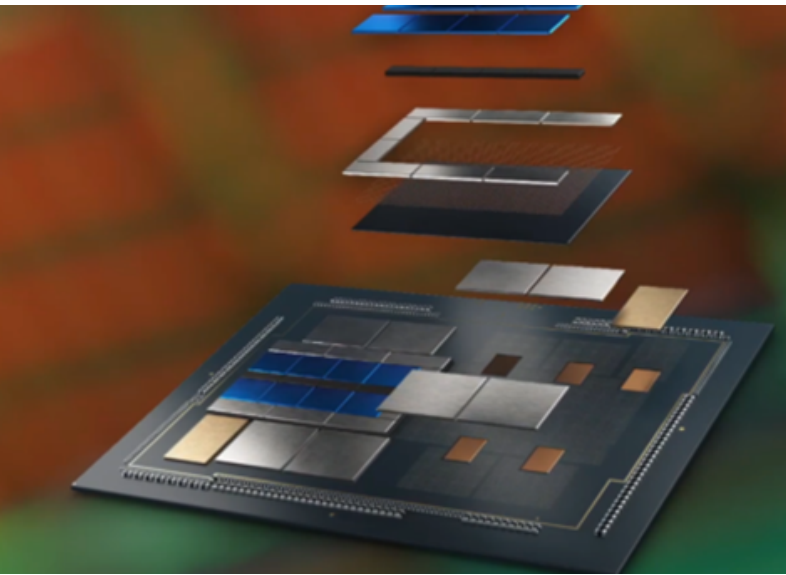


## IEEE - EPS - IESA WORKSHOP 2022

1st INTERNATIONAL WORKSHOP ON  
ADVANCED ELECTRONICS PACKAGING

1st and 2nd December 2022  
Taj MG Road, Bengaluru

# EVENT REPORT



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The India Electronics and Semiconductor Association (IESA) recently concluded the first edition of the Advanced Semiconductor Packaging Workshop, in association with the IEEE Electronics Packaging Society (IEEE-EPS) USA on December 1 and December 2, at the Taj MG Road, Bengaluru.

The two-day event attracted prominent figures from the government, industry, academia, policymakers, entrepreneurship, and student communities, who gathered to participate in an intellectually stimulating discourse on cutting-edge research and technological advancements in the semiconductor industry, with a specific focus on microsystems packaging and manufacturing. The workshop served as a pivotal platform for exchanging insights, best practices, and emerging trends, thereby providing a critical impetus for the development of innovative solutions and breakthroughs in the semiconductor industry.

The Hon'ble Minister for Electronics, IT/BT and Skill Development, Dr. Aswath Narayan, spoke passionately about the steps taken by the Government of India and the Government of Karnataka to operationalize the Fab and ATMP units. Ms. Gunjan Krishna, IAS, Commissioner for Industries & Commerce, highlighted the ecosystem components required for an ATMP/OSAT and how the state of Karnataka is working in tandem with the Government of India to set it up. The workshop also saw the participation of industry leaders, such as Mr. Vivek Tyagi, Chairman of IESA, Mr. Sam Karikalan, VP of IEEE-EPS and Executive Chair of the Workshop, Mr. K. Krishna Moorthy, CEO & President of IESA, and Suresh Subramaniam, General Chair of the Workshop.

The Advanced Semiconductor Packaging Workshop was aimed at fostering innovation in the semiconductor packaging segment. The event aimed to strengthen India's stance in the global semiconductor market by enabling chip designers in the country to venture beyond designing into packaging. The needs of the semiconductor industry, including manufacturing, education, and collaborative research, were also addressed during the workshop.

The successful collaboration between IESA and IEEE-EPS has paved the way for future joint initiatives and events that will further promote innovation in the semiconductor industry. The workshop's success is a testament to the Government of India and the Government of Karnataka's commitment to supporting the growth of the ESDM industry and creating a conducive environment for its development.

In conclusion, the first edition of the Advanced Semiconductor Packaging Workshop was a resounding success, bringing together industry experts, policymakers, and academia to foster innovation in the semiconductor packaging segment.

We extend our heartfelt gratitude to our esteemed industry partners, sponsors, exhibitors, and attendees for making this event a colossal platform for the illustrious Electronics & Semicon ecosystem discussions. IESA stands steadfast in its unwavering commitment to ensuring India's preeminence in the field of Electronics & Semicon.

**17+**  
**Speakers**

**5+**  
**Panel**  
**Discussions**

**xx +**  
**Attendees**

**10**  
**Sponsors**



# MISSION ACCOMPLISHED

## IEEE-EPS-IESA Packaging Workshop Reaches Core Objectives

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## KEY HIGHLIGHTS

- 1. Focus of IEEE EPS India Chapter:** The IEEE EPS India chapter is focused on enabling chip designers in India to go beyond design and into the packaging phase of semiconductor production.
- 2. Catalyst for the Semiconductor Industry:** This initiative serves as a catalyst for addressing the growing needs of the semiconductor industry, which is expanding to include manufacturing, education, and collaborative research.
- 3. Global Professionals in Various Disciplines:** The IEEE EPS India chapter brings together global leaders and professionals from various fields including industry, academia, government/policy makers, entrepreneurs, and students. These professionals come from diverse disciplines such as electrical, thermal, mechanical, and materials engineering and collaborate under one roof.
- 4. Global Collaboration Platform:** This workshop represents the first-ever collaboration between IESA and IEEE-EPS, the premier international forum for scientists and engineers involved in researching, designing, and developing groundbreaking advancements in microsystems packaging and manufacturing.

## KEY INSPIRATIONAL SPEAKERS



**Dr. Ashwath Narayan CN\***  
Hon'ble Minister of Electronics IT&BT, Minister  
of Skill Development, Entrepreneurship and  
Livelihood Government of Karnataka



**Ms. Gunjan Krishna**  
Commissioner for Industrial Development and  
Director, Department of Industries & Commerce  
Government of Karnataka



**Dr. Ravi M. Bhatkal, Ph.D.**  
Managing Director, India  
Element Solutions, Inc.  
Cookson India Private Limited



**Dr. Seung Wook Yoon, Ph.D**  
Corporate VP / Package Solution  
Planning & Strategy Samsung  
Electronics Co., Ltd.



**Ms. E Jan Vardaman**  
Founder & President  
TechSearch International, Inc.



**Mr. Subi Kengeri**  
Vice President, AI Systems Solutions  
Applied Materials, USA



**Prof. Rao Tummala**  
Director Emeritus  
Georgia Tech, USA



**Shri. Pradip Prabhakar**  
Commissioner, Dept of Technical Education  
Government of Karnataka

## THANK YOU TO OUR ESTEEMED SPONSORS



# GLIMPSES OF IEEE-EPS-IESA WORKSHOP 2022

